

MEMS DEVICE PACKAGING METHODS

ABSTRACT

[Para 37] A method of packaging a MEMS device that includes, for example, the steps of providing a MEMS die that has a MEMS device, a seal ring and bond pads disposed thereon, providing a MEMS package that has a recess, a seal ring and bond pads disposed thereon, positioning the MEMS die over the MEMS package to align the seal rings and bond pads, inserting the MEMS die and MEMS package into a vacuum chamber and evacuating gasses therefrom to form a controlled vacuum pressure therein, sealing the MEMS package and the MEMS die together at the seal rings to form a package having a hermitically sealed interior chamber and simultaneously forming electrical connections between the corresponding bond pads.

Figure 1